

TECHNOLOGY

COATING: EPOXY GLOB TOP / UV GLOB TOP
SILICONE
UNDERFILL
FILLING MASS

SUBSTRATES: THICK FILM CERAMIC
FR4, FR5, G10, G11, ROGERS
FLEX, RIGID FLEX, IMS
PYREX
...

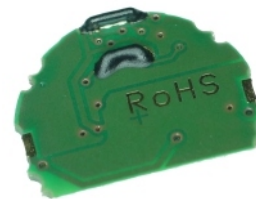
COLORS: TRANSPARENT
OPAQUE
BLACK
...

PROCESS: MANUAL
AUTOMATIC

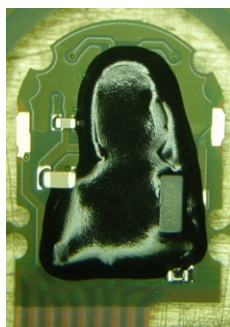
CHOOSING THE KIND OF RESIN AND THE MANUFACTURING PROCESS FOR THE MODULES' PROTECTION IS DEFINED IN COLLABORATION WITH THE CLIENT, ACCORDING TO THE PRODUCT SPECIFICATIONS.

GLOB TOP TECHNIQUES

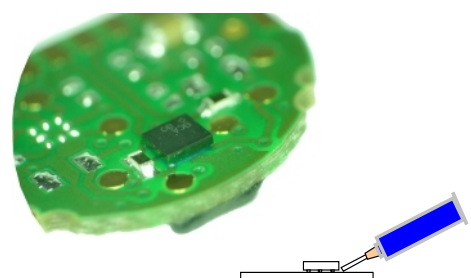
COATING



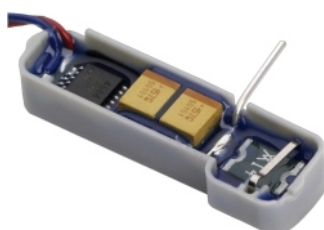
DAM & FILL



UNDERFILL (FLIP-CHIP, CSP, BGA)



FILLING MASS (SUPPORT AND PROTECTION)



HYBRID SA IS ABLE TO PROTECT MICRO-ELECTRONIC MODULES ACCORDING TO SHAPE AS WELL AS MINIMUM AND MAXIMUM HEIGHT SPECIFICATIONS. QUALIFIED STAFF, AT TIMES ASSISTED BY DISPENSING ROBOTS, ABLE TO SATISFY THE MOST DEMANDING PRODUCT NEEDS.